

PCTWORLD INTELLECTUAL PROPERTY ORGANIZATION
International BureauRTMP
COPY

INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁶: C09J 123/08, 4/06, C08F 255/02	A1	(11) International Publication Number: WO 97/16500 (43) International Publication Date: 9 May 1997 (09.05.97)
(21) International Application Number: PCT/US96/16924 (22) International Filing Date: 23 October 1996 (23.10.96) (30) Priority Data: 7/283142 31 October 1995 (31.10.95) ✓ JP (71) Applicant (for all designated States except US): MINNESOTA MINING AND MANUFACTURING COMPANY [US/US]; 3M Center, P.O. Box 33427, Saint Paul, MN 55133-3427 (US). (72) Inventors; and (75) Inventors/Applicants (for US only): KWATE, Kohichiro [JP/JP]; 3-8-17, Tamagawa-gakuen, Machida-city, Tokyo 194 (JP). ISHII, Shigeyoshi [JP/JP]; 29-4, Aihara 2-chome, Sagami-hara-city, Kanagawa pref. 229 (JP). (74) Agents: SKOLNICK, Steven, E. et al.; Minnesota Mining and Manufacturing Company, Office of Intellectual Property Counsel, P.O. Box 33427, Saint Paul, MN 55133-3427 (US).		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, HU, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, <u>SG</u> , SI, SK, TJ, TM, TR, TT, UA, UG, US, UZ, VN, ARIPO patent (KE, LS, MW, SD, SZ, UG), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published <i>With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>
(54) Title: REACTIVE HOT MELT COMPOSITION, COMPOSITION FOR PREPARATION OF REACTIVE HOT MELT COMPOSITION, AND FILM-FORM HOT MELT ADHESIVE (57) Abstract A composition for preparing a reactive hot melt composition comprises (a) a thermoplastic polymer which comprises a polyolefin having an epoxy group, and (b) a radiation polymerizable component containing (b-1) an aliphatic alkyl (meth)acrylate and (b-2) an acrylic compound having a functional group reactive with an epoxy group. A reactive hot melt composition is obtained by polymerizing this composition so as to polymerize the radiation polymerizable component. The reactive hot melt composition which can be easily hot melt coated, cross-linked quickly in the absence of radiation or moisture after bonding adherends, does not form moisture during cross-linking, and has high flowability during hot melting.		